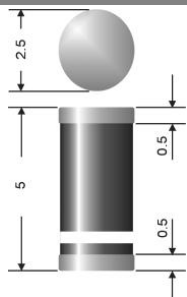


# SDA 2AK, SDA 4AK



Surface mount diode

## Bidirectional clamping diodes

SDA 2AK, SDA 4AK

Pulse Power Dissipation: 300 W

Stand-off voltage: 0,5...1,0 V

### Features

- Max. solder temperature: 260°C
- Plastic material has UL classification 94V-0

### Mechanical Data

- Plastic case Melf / DO-213AB
- Weight approx.: 0,12 g
- Terminals: plated terminals solderable per MIL-STD-750
- Mounting position: any
- Standard packaging: 5000 pieces per reel

1) Non-repetitive current pulse see curve  $I_{PPM} = f(t_r)$

2) Mounted on P.C. board with 25 mm<sup>2</sup> copper pads at each terminal

Absolute Maximum Ratings		$T_A = 25\text{ °C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
$P_{PPM}$	Peak pulse power dissipation (10/1000 $\mu$ s waveform) <sup>1)</sup> $T_a = 25\text{ °C}$	300	W
$P_{M(AV)}$	Steady state power dissipation <sup>2)</sup> , $T_a = 25\text{ °C}$	1	W
$I_{FSM}$	$T_a = \text{°C}$		A
$R_{thA}$	Max. thermal resistance junction to ambient <sup>2)</sup>	45	K/W
$R_{thT}$	Max. thermal resistance junction to terminal	10	K/W
$T_j$	Operating junction temperature	-50...+150	°C
$T_s$	Storage temperature	-50...+175	°C
$V_f$	Max. instant. forw. voltage $I_f = A$ <sup>3)</sup>		V
			V

Type	Stand-off voltage@ $I_D$		Breakdown voltage@ $I_T$		Test current $I_T$ mA	Max. clamping voltage@ $I_{PPM}$	
	$V_{WM}$ V	$I_D$ $\mu$ A	min. V	max. V		$V_C$ V	$I_{PPM}$ A
SDA 2AK	0,5	1000	0,8	1	1000	2	40
SDA 4AK	1	1000	1,6	2	1000	4	40

